

Electronic Patent Application Fee Transmittal

Application Number:	10571142
Filing Date:	22-Nov-2006
Title of Invention:	Semiconductor substrate cutting method
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Filer:	Joseph John Buczynski/Towanna Bolling
Attorney Docket Number:	46884-5461

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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1110